



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : WANG, Sung-Fei Confirmation No: 7610  
Appl. No. : 10/809,384  
Filed : March 26, 2004  
Title : BUMP STRUCTURE OF A SEMICONDUCTOR WAFER  
AND MANUFACTURING METHOD THEREOF

TC/A.U. : 2826  
Examiner : SANDVIK, Benjamin P.

Docket No.: : WANG3232/REF  
Customer No: : 23364

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of March 14, 2005, in connection with the above-identified application. The period for response to this Official Action has been extended to expire on July 14, 2005, by the filing herewith of a petition for a one month extension of time and payment of the required fee.

Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.